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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	925MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb5d4f35c4n

Advantage	Supporting Feature
Lowest system cost	• Requires as few as four power supplies to operate • Available in thermal composite flip chip ball-grid array (BGA) packaging • Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description

Technology	• TSMC's 28-nm process technology:
	  • Arria V GX, GT, SX, and ST—28-nm low power (28LP) process
	  • Arria V GZ—28-nm high performance (28HP) process
	• Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions)
	• 0.85 V, 1.1 V, or 1.15 V core nominal voltage

Packaging	• Thermal composite flip chip BGA packaging • Multiple device densities with identical package footprints for seamless migration between different device densities • Leaded(1), lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	• Enhanced 8-input ALM with four registers • Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	• M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) • M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) • Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

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(1) Contact Altera for availability.

Feature	Description	

Embedded Hard IP blocks	Variable-precision DSP	• Native support for up to four signal processing precision levels:
		  • Three 9 x 9, two 18 x 18, or one 27 x 27 multiplier in the same variable-precision DSP block
		  • One 36 x 36 multiplier using two variable-precision DSP blocks (Arria V GZ devices only)
		• 64-bit accumulator and cascade for systolic finite impulse responses (FIRs)
		• Embedded internal coefficient memory
		• Preadder/subtractor for improved efficiency

	Memory controller (Arria V GX, GT, SX, and ST only)	DDR3 and DDR2

	Embedded transceiver I/O	• Custom implementation:
		  • Arria V GX and SX devices—up to 6.5536 Gbps
		  • Arria V GT and ST devices—up to 10.3125 Gbps
		  • Arria V GZ devices—up to 12.5 Gbps
		• PCI Express® (PCIe®) Gen2 (x1, x2, or x4) and Gen1 (x1, x2, x4, or x8) hard IP with multifunction support, endpoint, and root port
		• PCIe Gen3 (x1, x2, x4, or x8) support (Arria V GZ only)
		• Gbps Ethernet (GbE) and XAUI physical coding sublayer (PCS)
		• Common Public Radio Interface (CPRI) PCS
		• Gigabit-capable passive optical network (GPON) PCS
		• 10-Gbps Ethernet (10GbE) PCS (Arria V GZ only)
		• Serial RapidIO® (SRIO) PCS
		• Interlaken PCS (Arria V GZ only)

Clock networks	• Up to 650 MHz global clock network • Global, quadrant, and peripheral clock networks • Clock networks that are not used can be powered down to reduce dynamic power	
Phase-locked loops (PLLs)	• High-resolution fractional PLLs • Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB) • Integer mode and fractional mode • LC oscillator ATX transmitter PLLs (Arria V GZ only)	

Feature	Description
FPGA General-purpose I/Os (GPIOs)	• 1.6 Gbps LVDS receiver and transmitter • 800 MHz/1.6 Gbps external memory interface • On-chip termination (OCT) • 3.3 V support [(2)]
External Memory Interface	Memory interfaces with low latency: • Hard memory controller-up to 1.066 Gbps • Soft memory controller-up to 1.6 Gbps
Low-power high-speed serial interface	• 600 Mbps to 12.5 Gbps integrated transceiver speed • Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps • Transmit pre-emphasis and receiver equalization • Dynamic partial reconfiguration of individual channels • Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) • PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) • Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only)
HPS (Arria V SX and ST devices only)	• Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing • Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces • System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers • On-chip RAM and boot ROM • HPS–FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa • FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller • ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage

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(2) Arria V GZ devices support 3.3 V with a 3.0 V V_{CCIO}.

Resource		Member Code							
		A1	A3	A5	A7	B1	B3	B5	B7
6 Gbps Transceiver		9	9	24	24	24	24	36	36
GPIO[3]		416	416	544	544	704	704	704	704
LVDS	Transmitter	67	67	120	120	160	160	160	160
	Receiver	80	80	136	136	176	176	176	176
PCIe Hard IP Block		1	1	2	2	2	2	2	2
Hard Memory Controller		2	2	4	4	4	4	4	4

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code	F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	—	—	—	—
A3	336	9	416	9	—	—	—	—
A5	336	9	384	18	544	24	—	—
A7	336	9	384	18	544	24	—	—
B1	—	—	384	18	544	24	704	24
B3	—	—	384	18	544	24	704	24
B5	—	—	—	—	544	24	704	36
B7	—	—	—	—	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.

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(3) The number of GPIOs does not include transceiver I/Os. In the Quartus® Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code			
		C3	C7	D3	D7
Transceiver	6 Gbps[4]	3 (9)	6 (24)	6 (24)	6 (36)
	10 Gbps[5]	4	12	12	20
GPIO[6]		416	544	704	704
LVDS	Transmitter	68	120	160	160
	Receiver	80	136	176	176
PCIe Hard IP Block		1	2	2	2
Hard Memory Controller		2	4	4	4

Related Information

- **High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook**
  Provides the number of LVDS channels in each device package.
- **Transceiver Architecture in Arria V Devices**
  Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Member Code	F672 (27 mm)			F896 (31 mm)			F1152 (35 mm)			F1517 (40 mm)		
	GPIO	XCVR		GPIO	XCVR		GPIO	XCVR		GPIO	XCVR	
		6-Gbps	10-Gbps		6-Gbps	10-Gbps		6-Gbps	10-Gbps		6-Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	—	—	—	—	—	—
C7	—	—	—	384	6 (18)	8	544	6 (24)	12	—	—	—
D3	—	—	—	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	—	—	—	—	—	—	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps

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[4] The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.

[5] Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

[6] The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Related Information

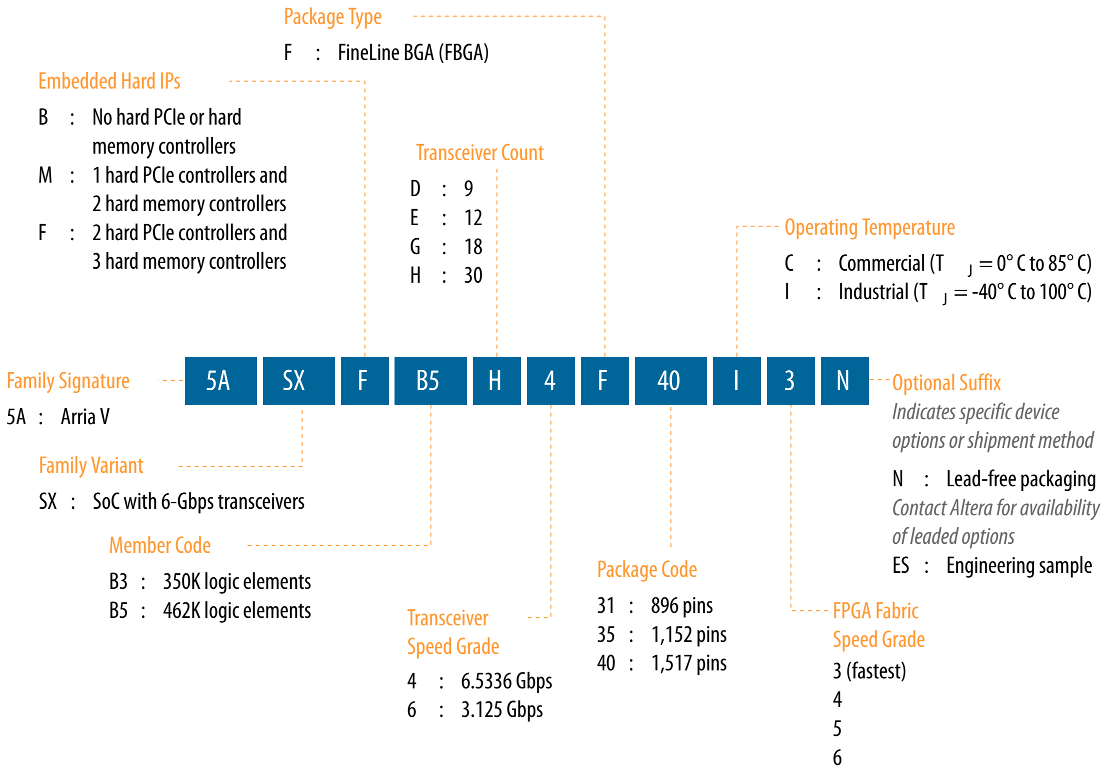
Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 4: Sample Ordering Code and Available Options for Arria V SX Devices

The –3 FPGA fabric speed grade is available only for industrial temperature devices.



Maximum Resources

Table 10: Maximum Resource Counts for Arria V SX Devices

Resource		Member Code	
		B3	B5
Logic Elements (LE) (K)		350	462
ALM		132,075	174,340
Register		528,300	697,360
Memory (Kb)	M10K	17,290	22,820
	MLAB	2,014	2,658
Variable-precision DSP Block		809	1,090
18 x 18 Multiplier		1,618	2,180

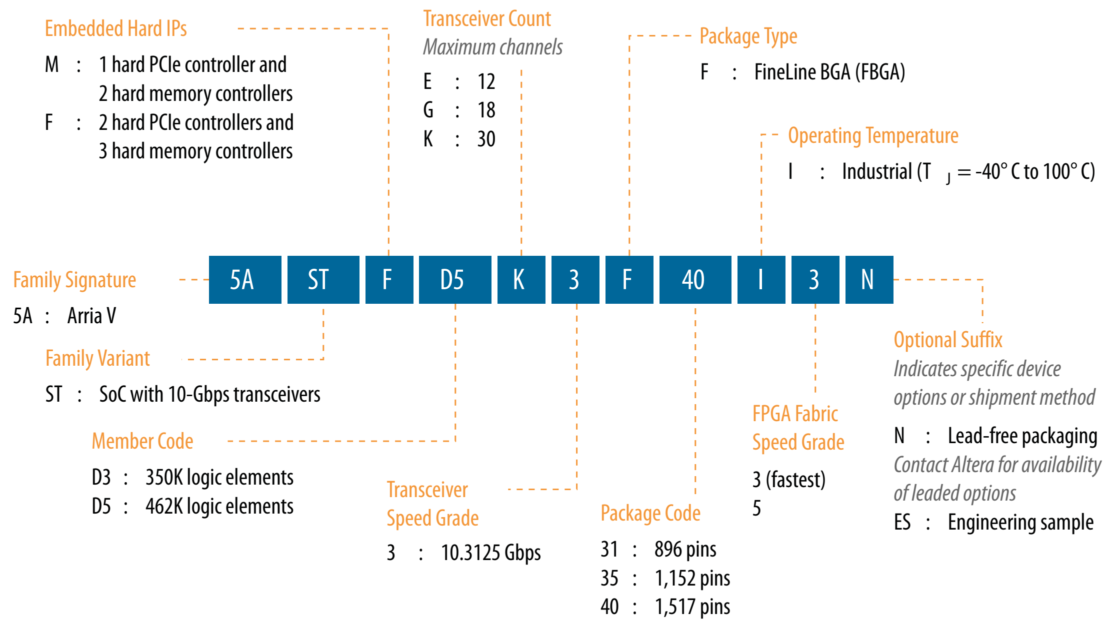
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

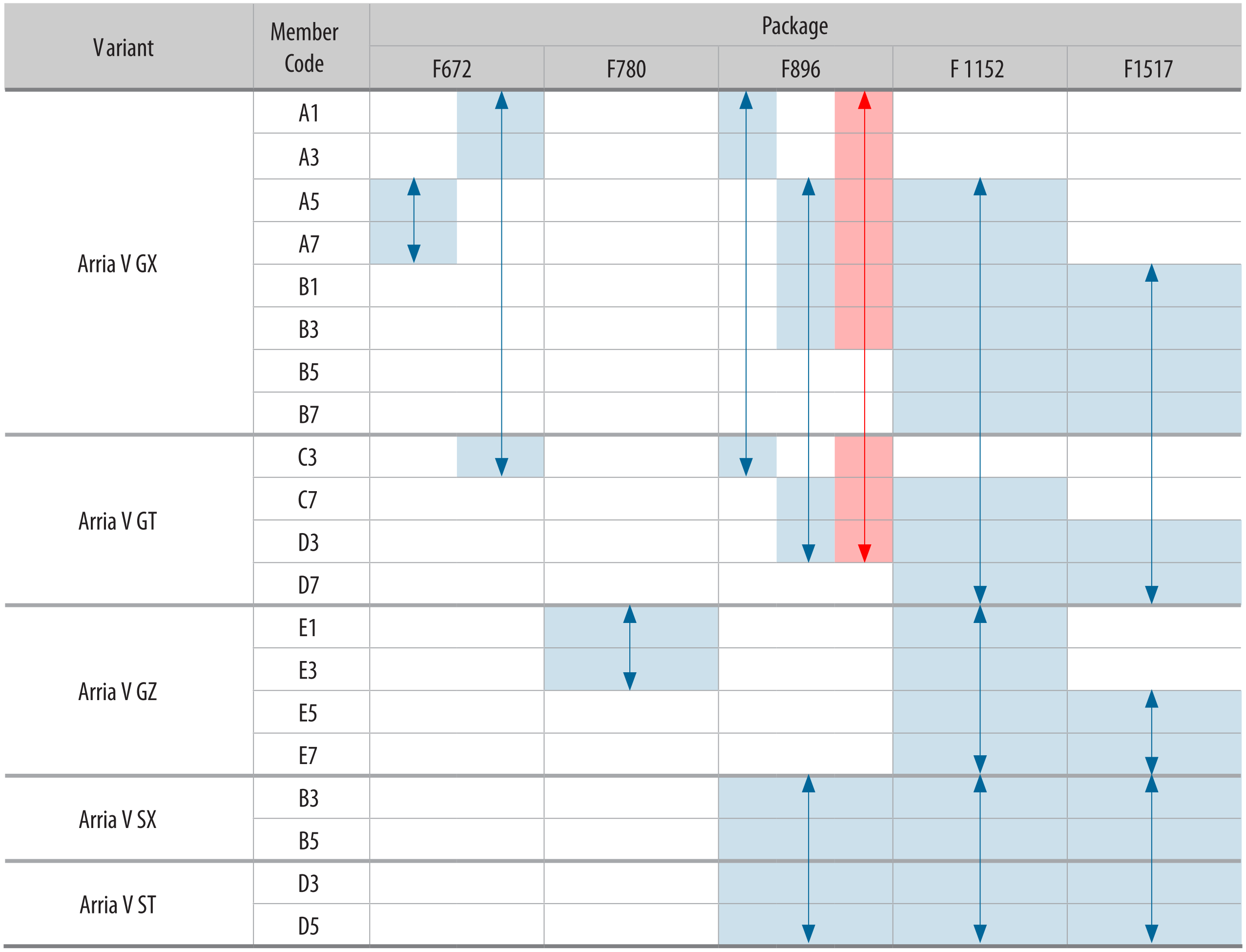
Table 12: Maximum Resource Counts for Arria V ST Devices

Resource		Member Code	
		D3	D5
Logic Elements (LE) (K)		350	462
ALM		132,075	174,340
Register		528,300	697,360
Memory (Kb)	M10K	17,290	22,820
	MLAB	2,014	2,658
Variable-precision DSP Block		809	1,090
18 x 18 Multiplier		1,618	2,180
FPGA PLL		14	14
HPS PLL		3	3
Transceiver	6-Gbps	30	30
	10-Gbps(9)	16	16

I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.

Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator				18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier		
Arria V GX	A1	240	720	480	240	—	240	240
	A3	396	1,188	792	396	—	396	396
	A5	600	1,800	1,200	600	—	600	600
	A7	800	2,400	1,600	800	—	800	800
	B1	920	2,760	1,840	920	—	920	920
	B3	1,045	3,135	2,090	1,045	—	1,045	1,045
	B5	1,092	3,276	2,184	1,092	—	1,092	1,092
	B7	1,156	3,468	2,312	1,156	—	1,156	1,156
Arria V GT	C3	396	1,188	792	396	—	396	396
	C7	800	2,400	1,600	800	—	800	800
	D3	1,045	3,135	2,090	1,045	—	1,045	1,045
	D7	1,156	3,468	2,312	1,156	—	1,156	1,156
Arria V GZ	E1	800	2,400	1,600	800	400	800	800
	E3	1,044	3,132	2,088	1,044	522	1,044	1,044
	E5	1,092	3,276	2,184	1,092	546	1,092	1,092
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139
Arria V SX	B3	809	2,427	1,618	809	—	809	809
	B5	1,090	3,270	2,180	1,090	—	1,090	1,090
Arria V ST	D3	809	2,427	1,618	809	—	809	809
	D5	1,090	3,270	2,180	1,090	—	1,090	1,090

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Arria V devices contain two types of memory blocks:

- 20 Kb M20K or 10 Kb M10K blocks—blocks of dedicated memory resources. The M20K and M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Arria V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB. You can also configure these ALMs, in Arria V GZ devices, as ten 64 x 1 blocks, giving you one 64 x 10 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Arria V Devices

Table 16: Embedded Memory Capacity and Distribution in Arria V Devices

Variant	Member Code	M20K		M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Arria V GX	A1	—	—	800	8,000	741	463	8,463
	A3	—	—	1,051	10,510	1538	961	11,471
	A5	—	—	1,180	11,800	1877	1,173	12,973
	A7	—	—	1,366	13,660	2317	1,448	15,108
	B1	—	—	1,510	15,100	2964	1,852	16,952
	B3	—	—	1,726	17,260	3357	2,098	19,358
	B5	—	—	2,054	20,540	4052	2,532	23,072
	B7	—	—	2,414	24,140	4650	2,906	27,046
Arria V GT	C3	—	—	1,051	10,510	1538	961	11,471
	C7	—	—	1,366	13,660	2317	1,448	15,108
	D3	—	—	1,726	17,260	3357	2,098	19,358
	D7	—	—	2,414	24,140	4650	2,906	27,046
Arria V GZ	E1	585	11,700	—	—	4,151	2,594	14,294
	E3	957	19,140	—	—	6,792	4,245	23,385
	E5	1,440	28,800	—	—	7,548	4,718	33,518
	E7	1,700	34,000	—	—	8,490	5,306	39,306
Arria V SX	B3	—	—	1,729	17,290	3223	2,014	19,304
	B5	—	—	2,282	22,820	4253	2,658	25,478

Related Information

External Memory Interface Spec Estimator
For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Arria V devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at less than 170 mW
- 10 Gbps transceivers at less than 165 mW
- 6 Gbps transceivers at less than 105 mW

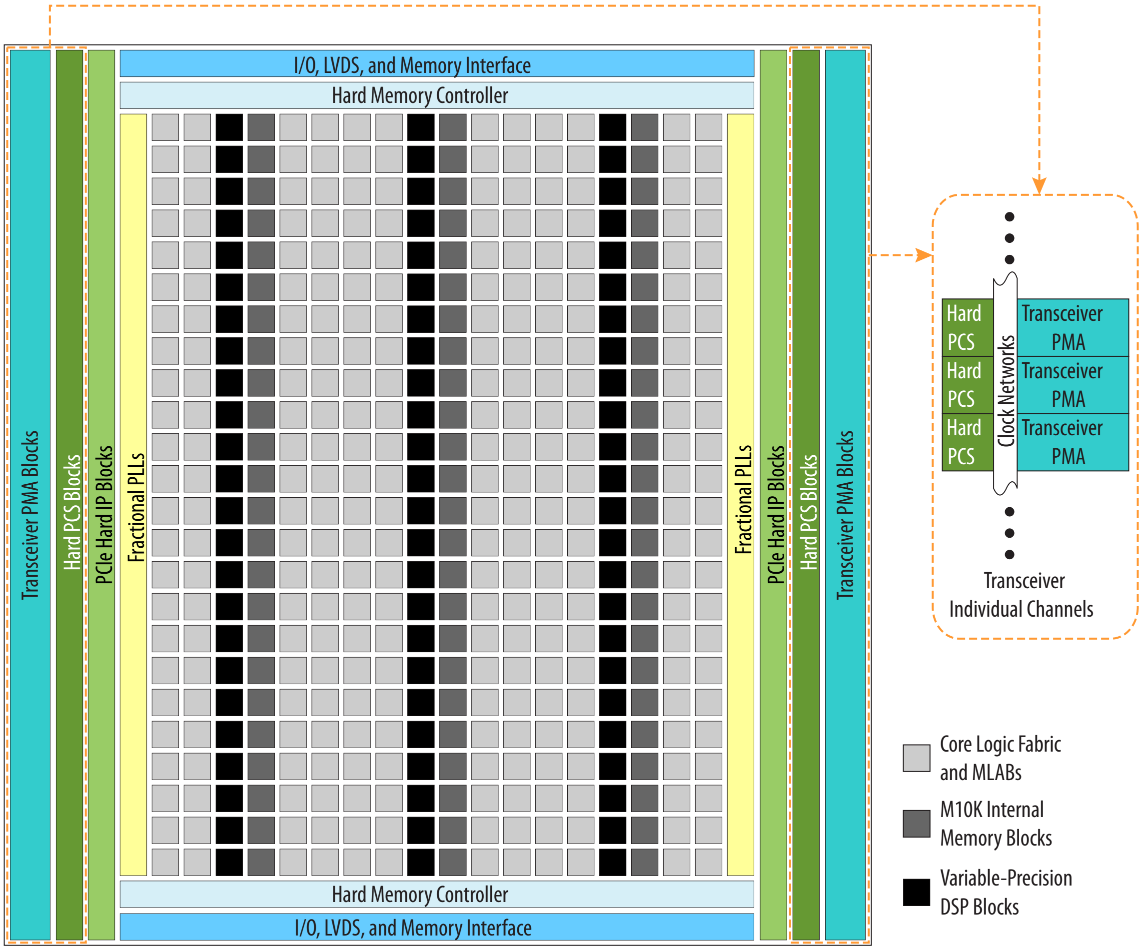
Arria V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left and right outer edges of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

The following figures are graphical representations of a top view of the silicon die, which corresponds to a reverse view for flip chip packages. Different Arria V devices may have different floorplans than the ones shown in the figures.

Figure 9: Device Chip Overview for Arria V GX and GT Devices



PCS Support(13)	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8)	2.5 and 5.0	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • PIPE 2.0 interface to the core logic	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • Rate match FIFO • PIPE 2.0 interface to the core logic
PCIe Gen2(14) (x1, x2, x4)			
GbE	1.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • Rate match FIFO
XAUI(15)	3.125	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • XAUI state machine for bonding four channels	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • XAUI state machine for realigning four channels • Deskew FIFO circuitry
SDI	0.27(16), 1.485, 2.97	• Phase compensation FIFO • Byte serializer	• Byte deserializer • Phase compensation FIFO
GPON(17)	1.25 and 2.5		
CPRI(18)	0.6144 to 6.144	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • TX deterministic latency	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • RX deterministic latency

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(13) Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.
(14) PCIe Gen2 is supported only through the PCIe hard IP.
(15) XAUI is supported through the soft PCS.
(16) The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
(17) The GPON standard does not support burst mode.
(18) CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet	4 x 10.3125	• TX FIFO • 64B/66B encoder • Scrambler • Alignment marker insertion • Gearbox • Block stripper	• RX FIFO • 64B/66B decoder • Descrambler • Lane reorder • Deskew • Alignment marker lock • Block synchronization • Gear box • Destripper
100GBASE-R Ethernet	10 x 10.3125		
40G and 100G OTN	(4 +1) x 11.3	• TX FIFO • Channel bonding • Byte serializer	• RX FIFO • Lane deskew • Byte deserializer
	(10 +1) x 11.3		
GbE	1.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • GbE state machine	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • GbE state machine
XAUI	3.125 to 4.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • XAUI state machine for bonding four channels	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • SRIO V2.1-compliant x2 and x4 channel bonding	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • SRIO V2.1-compliant x2 and x4 deskew state machine

SoC with HPS

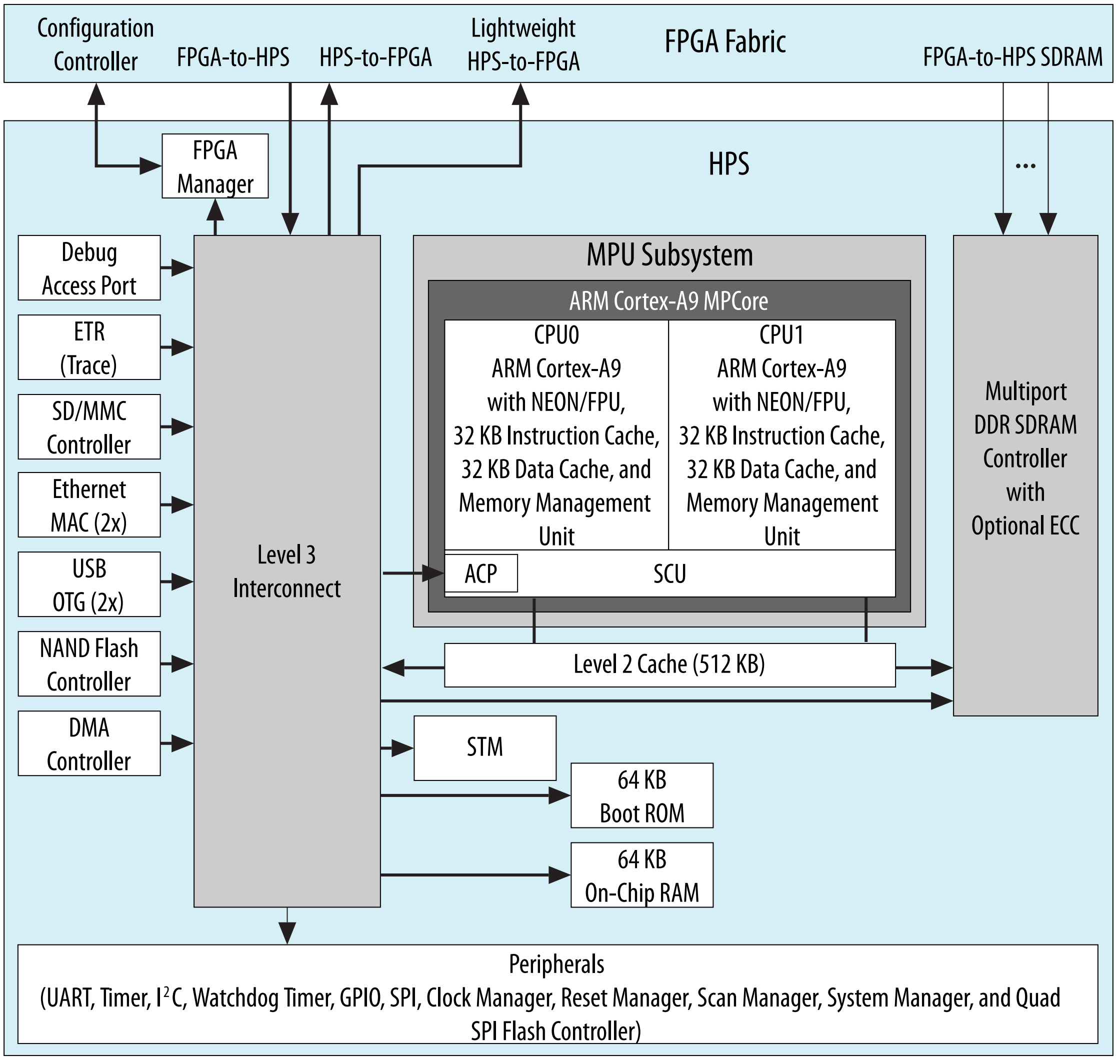
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS–FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS–FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 533 MHz (1066 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or partially reconfigure the FPGA fabric at any time under software control. The HPS can also configure other FPGAs on the board through the FPGA configuration controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

- **Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines**
  Provides detailed information about power supply pin connection guidelines and power regulator sharing.
- **Arria V GZ Device Family Pin Connection Guidelines**
  Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Qsys system integration tool in the Quartus Prime software.

For software development, the ARM-based SoC devices inherit the rich software development ecosystem available for the ARM Cortex-A9 MPCore processor. The software development process for Altera SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Altera sales team.

You can begin device-specific firmware and software development on the Altera SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

Altera Worldwide Sales Support

Dynamic and Partial Reconfiguration

The Arria V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA, PCS, and PCIe hard IP blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Altera simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Quartus Prime design software. With the Altera solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Table 23: Configuration Modes and Features of Arria V Devices

Arria V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V(19) programming voltages and several configuration modes.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressio	Design Security	Partial Reconfiguratio (20)	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	—	Yes	Yes	—	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	—	—

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(19) Arria V GZ does not support 3.3 V.

(20) Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Altera for support.

Document Revision History

Date	Version	Changes
December 2015	2015.12.21	- Updated RoHS and optional suffix information in sample ordering code and available options diagrams for Arria V GX and GT devices. - Changed instances of *Quartus II* to *Quartus Prime*.
January 2015	2015.01.23	- Updated package dimension for Arria V GZ H780 package from 29 mm to 33 mm. - Updated dual-core ARM Cortex-A9 MPCore processor maximum frequency from 800 MHz to 1.05 GHz.
December 2013	2013.12.26	- 10-Gbps Ethernet (10GbE) PCS and Interlaken PCS are for Arria V GZ only. - Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. - Added link to **Altera Product Selector** for each device variant. - Added leaded package options. - Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. - Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F896 package from 170 to 250. - Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1152 package from 350 to 385. - Corrected FPGA GPIO for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 F1517 package from 528 to 540. - Corrected LVDS Transmitter for Arria V SX B3 and B5 as well as Arria V ST D3 and D5 devices from 121 to 120. - Added links to Altera's **External Memory Spec Estimator** tool to the topics listing the external memory interface performance. - Added x2 for PCIe Gen3, Gen 2, and Gen 1.
August 2013	2013.08.19	- Removed the note about the PCIe hard IP on the right side of the device in the F896 package of the Arria V GX variant. These devices do not have PCIe hard IP on the right side. - Added transceiver speed grade 6 to the available options of the Arria V SX variant. - Corrected the maximum LVDS transmitter channel counts for the Arria V GX A1 and A3 devices from 68 to 67. - Corrected the maximum FPGA GPIO count for Arria V ST D5 devices from 540 to 528.

Date	Version	Changes
July 2012	2.1	• Added –I3 speed grade to Figure 1 for Arria V GX devices. • Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	• Restructured the document. • Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. • Added Table 1, Table 3, Table 12, Table 15, and Table 16. • Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. • Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. • Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. • Text edits throughout the document.
February 2012	1.3	• Updated Table 1–7 and Table 1–8. • Updated Figure 1–9 and Figure 1–10. • Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	• Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. • Added "SoC FPGA with HPS" section. • Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. • Updated Figure 1–5. • Added Figure 1–6. • Minor text edits.
August 2011	1.0	Initial release.